



## Product Change Notification / KSRA-15TQLX387

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**Date:**

19-Apr-2021

**Product Category:**

Memory

**PCN Type:**

Manufacturing Change

**Notification Subject:**

CCB 4633 Initial Notice: Qualification of MMT as a new assembly site for SST49LF008A device family available in 32L PLCC (11.5x14x3.37mm) package

**Affected CPNs:**

[KSRA-15TQLX387\\_Affected\\_CPN\\_04192021.pdf](#)  
[KSRA-15TQLX387\\_Affected\\_CPN\\_04192021.csv](#)

**Notification Text:**

**PCN Status:** Initial notification

**PCN Type:** Manufacturing Change

**Microchip Parts Affected:** Please open one of the files found in the Affected CPNs section.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

**Description of Change:** Qualification of MMT as a new assembly site for SST49LF008A device family available in 32L PLCC (11.5x14x3.37mm) package

**Pre and Post Change Summary:**

	Pre Change	Post Change
Assembly Site	Lingsen Precision Industries, LTD. (LPI)	Microchip Technology Thailand

		(MMT)
Wire material	Au	Au
Die attach material	8340	3280
Molding compound material	G600	G600
Lead frame material	C151	A194
Lead frame paddle size	181x261 mils	200x365 mils
	See attached pre and post change comparison	

**Impacts to Data Sheet:** None

**Change Impact:**None

**Reason for Change:**To improve on-time delivery performance by qualifying MMT as a new assembly site.

**Change Implementation Status:**In Progress

**Estimated Qualification Completion Date:**June 2021

Note: Please be advised the qualification completion times may be extended because of unforeseen business conditions however implementation will not occur until after qualification has completed and a final PCN has been issued. The final PCN will include the qualification report and estimated first ship date. Also note that after the estimated first ship date guided in the final PCN customers may receive pre and post change parts.

**Time Table Summary:**

	April 2021					-->	June 2021				
	1 4	1 5	1 6	1 7	1 8		2 3	2 4	2 5	2 6	2 7
Initial PCN Issue Date				X							
Qual Report Availability								X			
Final PCN Issue Date								X			

**Method to Identify Change:** Traceability code

**Qualification Plan:**Please open the attachments included with this PCN labeled as PCN\_#\_Qual\_Plan.

**Revision History:**April 19, 2021: Issued initial notification.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

**Attachments:**

[PCN\\_KSRA-15TQLX387\\_Pre and Post Change Summary.pdf](#)

[PCN\\_KSRA-15TQLX387\\_Qual\\_Plan.pdf](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

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If you wish to [change your PCN profile, including opt out](#), please go to the [PCN home page](#) select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections.

Affected Catalog Part Numbers (CPN)

SST49LF008A-33-4C-NHE

SST49LF008A-33-4C-NHE-PP013

SST49LF008A-33-4C-NHE-PP009

SST49LF008A-33-4C-NHE-T

SST49LF008A-33-4C-NHE-PP013-T

SST49LF080A-33-4C-NHE

SST49LF080A-33-4C-NHE-PP009

SST49LF080A-33-4C-NHE-T

**CCB 4633**  
**Pre and Post Change Summary**  
**PCN#:KSRA-15TQLX387**



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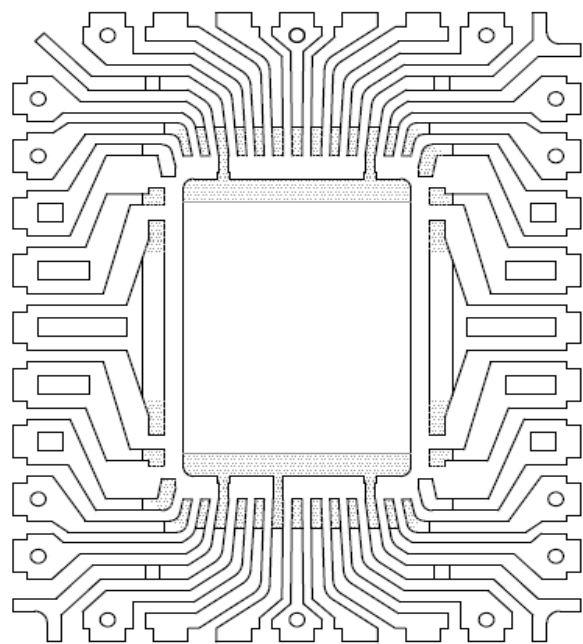


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# Lead frame comparison

Pre change

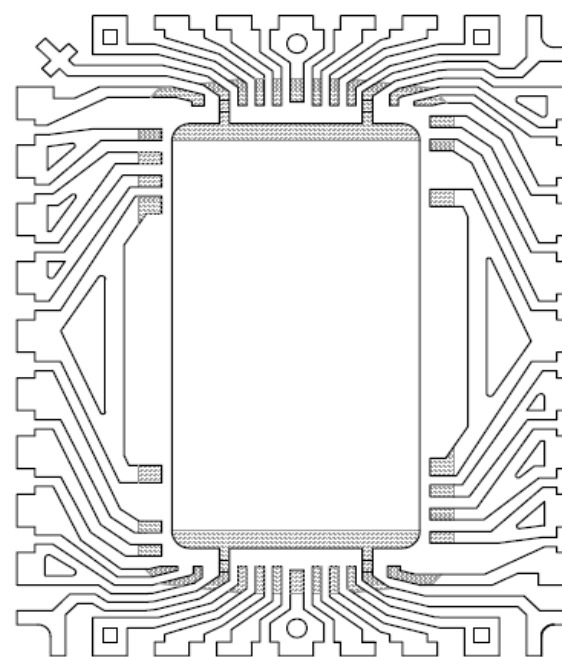
LPI



PAD SIZE:181x261 MILS  
FUSED LEAD ON PIN#16

Post Change

MMT



PAD SIZE:200x365 MILS  
NON-FUSED LEAD ON PIN#16



**MICROCHIP**

# **QUALIFICATION PLAN SUMMARY**

**PCN#: KSRA-15TQLX387**

**Date**

**April 01, 2021**

**Qualification of MMT as a new assembly site for  
SST49LF008A device family available in 32L PLCC  
(11.5x14x3.37mm) package**

**Purpose: Qualification of MMT as a new assembly site for SST49LF008A device family available in 32L PLCC (11.5x14x3.37mm) package**

**CCB No.: 4633**

<u>Misc.</u>	Assembly site	MMT
	BD Number	BDM-002908/A
	MP Code (MPC)	U04071P3XF33
	Part Number (CPN)	SST49LF080A-33-4C-NHE
	MSL information	MSL-3/245
	Assembly Shipping Media (T/R, Tube/Tray)	TUBE
	Base Quantity Multiple (BQM)	30
	Reliability Site	MTAI
<u>Lead-Frame</u>	Paddle size	200x365 mils
	Material	A194
	DAP Surface Prep	Ag Ring Plated
	Treatment	None
	Process	Etched
	Lead-lock	No
	Part Number	10103212
	Lead Plating	Matte Tin
	Strip Size	8.749x2.756 in.
	Strip Density	24 units/strip
<u>Bond Wire</u>	Material	Au
<u>Die Attach</u>	Part Number	3280
	Conductive	Yes
<u>MC</u>	Part Number	G600
<u>PKG</u>	PKG Type	PLCC
	Pin/Ball Count	32
	PKG width/size	11.5x14x3.37mm



Test Name	Conditions	Sample Size	Spares per Lot (should be properly identified)	Qty of Lots	Total Units	Fail Accept Qty	Est. Dur. Days	Test Site	Special Instructions
<b>Standard Pb-free Solderability</b>	J-STD-002 ; Perform 8 hour steam aging for Matte tin finish and 1 hour steam aging for NiPdAu finish prior to testing.  Standard Pb-free: Matte tin/ NiPdAu finish, SAC solder, wetting temp 245°C for both SMD & through hole packages.	22	5	1	27	> 95% lead coverage	5	MTAI	Standard Pb-free solderability is the requirement. SnPb solderability (backward solderability- SMD reflow soldering) is required for any plating related changes and highly recommended for other package BOM changes.
<b>Backward Solderability</b>	J-STD-002 ; Perform 8 hours steam aging for Matte tin finish and 1 hour steam aging for NiPdAu finish prior to testing.  Backward: Matte tin/ NiPdAu finish, SnPb solder, wetting temp 215°C for SMD.	22	5	1	27	> 95% lead coverage	5	MTAI	
<b>Wire Bond Pull - WBP</b>	Mil. Std. 883-2011	5	0	3	15	0 fails after TC	5	MMT/MTAI	30 bonds from a minimum of 5 devices.
<b>Wire Bond Shear - WBS</b>	CDF-AEC-Q100-001	5	0	3	15		5	MMT/MTAI	30 bonds from a minimum of 5 devices.
<b>Wire Sweep</b>		5	0	3	15	0		MMT	Required for any reduction in wire bond thickness.
<b>External Visual</b>	Mil. Std. 883-2009/2010								
		All devices prior to submission for qualification testing	0	3	ALL	0	5	MMT/ MTAI	
<b>Preconditioning - Required for surface mount devices</b>	+150°C Bake for 24 hours, moisture loading requirements per MSL level + 3X reflow at peak reflow temperature per Jedec-STD-020E for package type; Electrical test pre and post stress at +25°C. MSL-3@245°C	231	15	3	738	0	15	MTAI	Spares should be properly identified. 77 parts from each lot to be used for HAST, Autoclave, Temp Cycle test.
<b>HAST</b>	+130°C/85% RH for 96 hours. Electrical test pre and post stress at +25°C and hot temp.	77	5	3	246	0	10	MTAI	Spares should be properly identified. Use the parts which have gone through Pre-conditioning.
<b>Unbiased HAST</b>	+130°C/85% RH for 96 hrs. Electrical test pre and post stress at +25°C.	77	5	3	246	0	10	MTAI	Spares should be properly identified. Use the parts which have gone through Pre-conditioning.
<b>Temp Cycle</b>	-65°C to +150°C for 500 cycles. Electrical test pre and post stress at hot temp; 3 gram force WBP, on 5 devices from 1 lot, test following Temp Cycle stress.	77	5	3	246	0	15	MTAI	Spares should be properly identified. Use the parts which have gone through Pre-conditioning.